

STYRENE RESIN COMPOSITION, AND MOLDED ARTICLE THEREOF

ABSTRACT

Provided are a styrene resin composition for use in electronic component packaging such as embossed carrier tape, a sheet which has a large drawing ratio (pocket depth) and in which pockets exhibiting superior transparency and strength and can be thermoformed, and a carrier tape which is thermoformed from the sheet and which allows the verification of letters and the like formed on packaged electronic components from outside the pockets. The electronic component packaging sheet comprises: (A) 29-65 mass parts of a styrene-conjugated diene block copolymer; (B) 51-15 mass parts of a polystyrene resin; and (C) 20-9 mass parts of an impact resistant polystyrene resin. Components (A)-(C) each have a weight average molecular weight (Mw) within a specified range.

No suitable figure